#### Vertex Detector Working Group

Sunday, July 13, 3:30-5:30 p.m.

3:30-4:00 LCFI Status Report4:00-4:30 CCD Radiation Damage Studies4:30-5:00 Status of LC R&D at Oklahoma5:00-5:30 Technology Options

Tuesday, July 15, 8:30-10:30 a.m.

9:00-10:30 Discussion

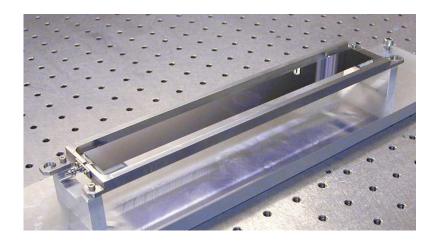
Chris Damerell, Rutherford Laboratory Olya Igonkina, Oregon Patrick Skubic, Oklahoma Chris Damerell, Rutherford Laboratory

Session convenors: Jim Brau & Marco Battaglia

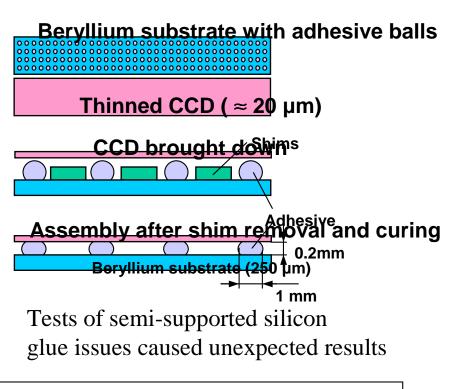
# A CCD-based vertex detector, Chris Damerell on behalf of the LCFI Collaboration

## **R&D programme**

- Development of novel CCDs and readout electronics
- Development of thinnest possible detector layers
- Physics studies



Tests of unsupported silicon

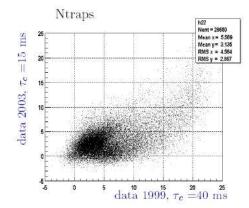


#### CCD Radiation Damage Studies, Olya Igonkina

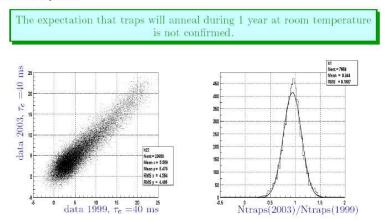
Changing the delay between signal injection and start of read out from 40 ms to 15 ms showed that the

filling time  $\tau_c$  is of the order of tens ms!

which contradicts to the expectation that  $\tau_c$  is of the order of ns (C. Damerrel, RAL-P-95-008)



Comparison of the 1999 and 2003 data before irradiation with electrons (collected under exactly the same conditions) shows same amount of traps in the same pixels.



#### Conclusions

After 4 years the CCD still had the same traps – no signicant annealing at room temperature is observed.

Traps filling with signal charge takes noticeable time – much larger than the time signal spend in each pixel.

We expect that the increased readout speed will lead to decrease of charge transfer ineciency.

### Status of LC R&D Proposals at Oklahoma, Patrick Skubic

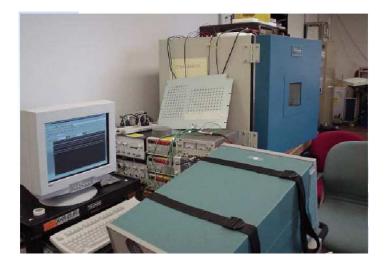
#### NSF Proposal

1 1 ----

- UCLC proposal: "Development and design of an LC ASIC for CCD readout and data reduction"
  - » Three year project
  - » Collaboration between OU, Boston U. (Ulrich Heintz), and Fermilab (William Wester)
  - » Previous experience on ATLAS pixel detector which uses IBM deep-submicron process

Tests at OU with VXD3 CCD Started (with help from Jim Brau and Nick Sinev)

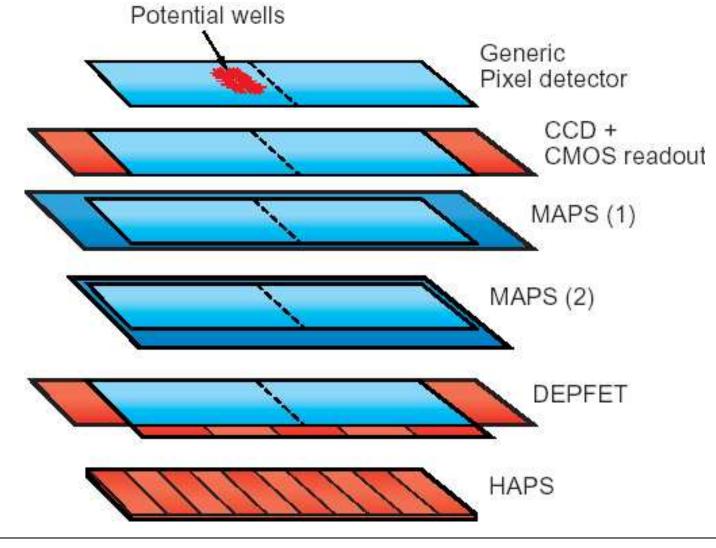




#### Conclusions

- CCD Tests at OU have been Started
- Software Tools for VLSI Design are Installed and Tested
- Contacts with Others Interested in Vertex Detector Readout have been made
  - » Oregon/Yale group
  - » LCFI group
  - » SLAC
  - » Fermilab

LC vertex detector technology options, Chris Damerell



#### Detector Working Group: Tracking

#### 13 talks

Sunday, July 13, 1:00-3:00

1:00-1:15 Welcome and Introduction	Bruce Schumm
1:15-1:40 JLC Tracking Report	Norik Khalatyan
1:40-2:05 Status of Linear Collider TPC R&D	Ron Settles
2:05-2:40 Update on TPC R&D In Canada	Dean Karlen
2:40-3:00 Open for discussion	

Monday, July 14, 10:55-12:55

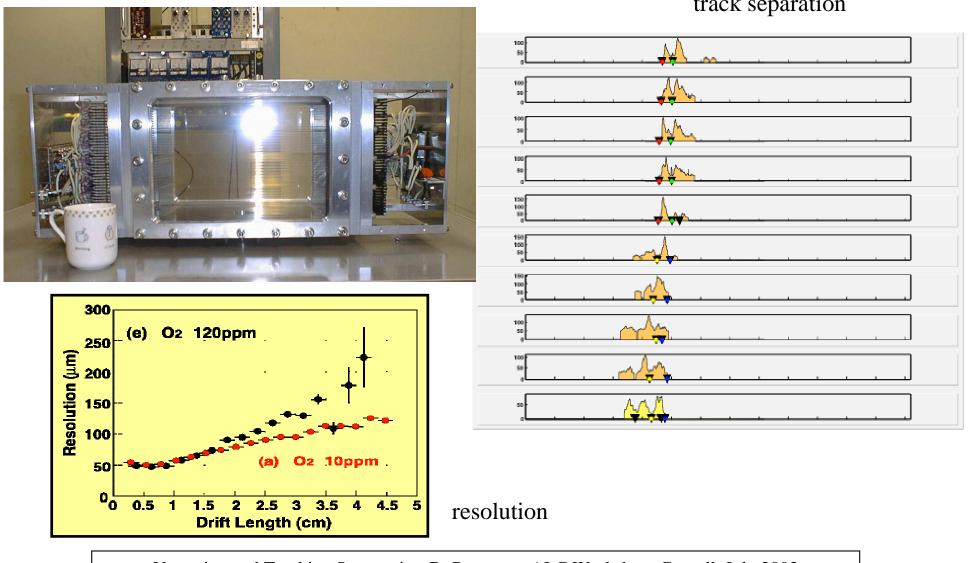
10:55-11:15	Negative Ion TPC for the Linear Collider	Alexander Schreiner
11:15-11:35	Commissioning of a MicroMegas TPC	Mike Ronan
11:35-11:55	Scintillating Fiber Intermediate Tracker R&D	Rick Van Kooten
11:55-12:15	Silicon Drift R&D at Wayne State	Rene Bellwied
12:15-12:30	Update on Frequency-Scanned Interferometry	Haijun Yang
12:30-12:55	Open for Discussion	

Tuesday, July 15, 10:55-12:55

10:55-11:15	Overview of the Strip-based SD Tracker	John Jaros
11:15-11:35	Long Shaping-Time Readout R&D	Bruce Schumm
11:35-11:55	Strip-based SD Pattern Recognition: Forward	Norman Graf
11:55-12:15	South Carolina Tracking	Achim Weidemann
12:15-12:35	First Mass Production of Gas Electron Multipliers	Ian Shipsey
12:35-12:55	Open for Discussion	

Session convenors: Bruce Schumm, Dean Karlen & Keith Riles

### JLC Tracking Report, Norik Khalatyan



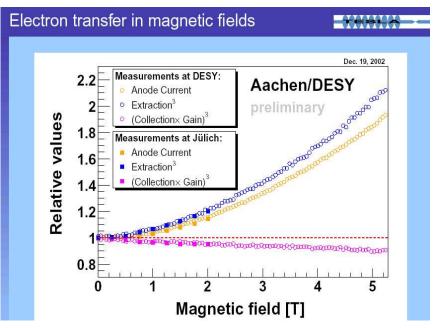
track separation

#### Selected LC TPC R&D Results, Ron Settles



Saclay 2T magnet

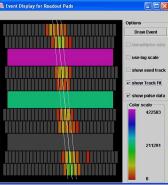
# GEM electron transfer In magnetic fields



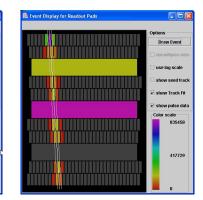
## TPC R&D in Canada, Dean Karlen



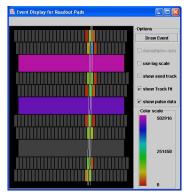
0 Tesla

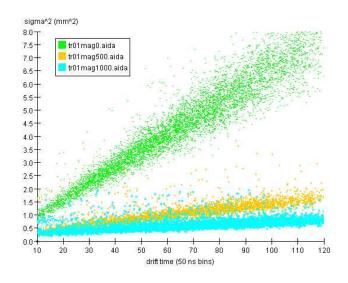


0.45 Tesla





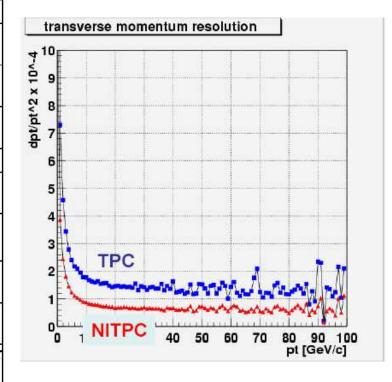




#### UCLC proposal

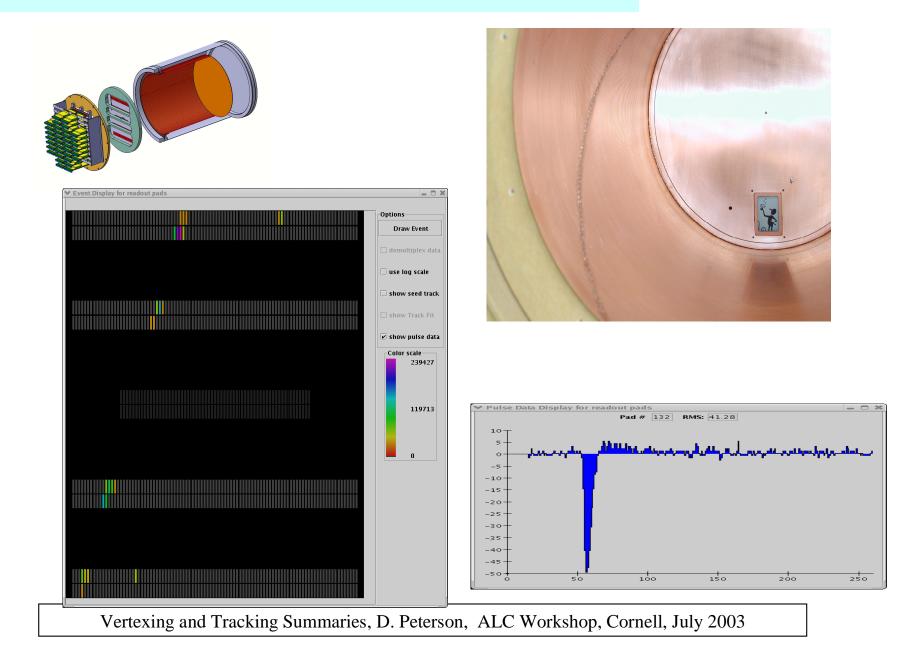
## Negative Ion TPC, Alexander Schreiner

Parameter	TPC	NITPC	Comments
objective	Central E		
geometry	azimu z=-		
material	gas:Ar	gas: He/CS <sub>2</sub> (80/20)	for radiation length
drift velocity	4.5[cm/µs]	20[m/s]*E[kV/cm]	Ar/CH <sub>4</sub> /CO <sub>2</sub> (97:5:2)
<i<sub>drift&gt;</i<sub>	1.35 m	33 cm	NITPC is divided into 12 sections azimuthally and TPC into 2 along z
$\sigma_{ m long}$	4 mm	0.4 mm	
$\sigma_{tr}$	0.68 mm		$0.07 \cdot \sqrt{L[cm]/E[kV/cm]}$
N <sub>s</sub> of samples/track	144	104	depends on the gas
<i>N<sub>i</sub></i> of e per measurement	140	1	
$\sigma_{\!_{z}meas}$	3 mm	2 mm*	$\sigma = \sigma / f$
$\sigma_{\!\scriptscriptstyle azim\ meas}$	0.1 mm	0.4 mm	$\sigma_{meas} = \sigma_{dif} / \sqrt{N}$



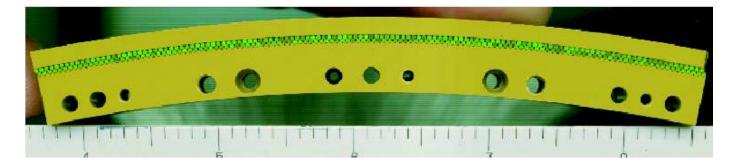
\*Simulation showed a bad resolution in the direction along wires

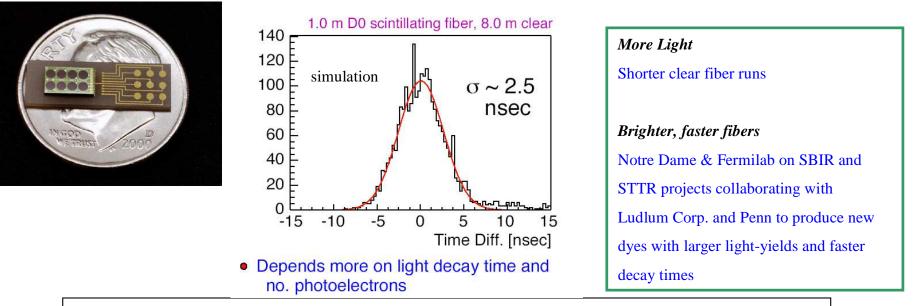
#### Commissioning of a Large Micromegas TPC, Mike Ronan



# **R&D of Scintillating Fibers for Intermediate Tracking and Bunch Id** Rick Van Kooten

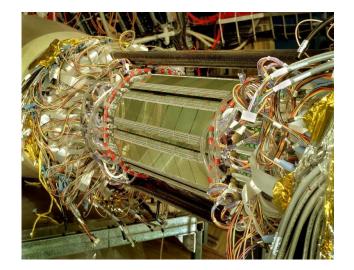
Motivation is to provide ~1 ns time stamp for each track to identify background tracks coming from multiple collisions within the integration time of detector components.

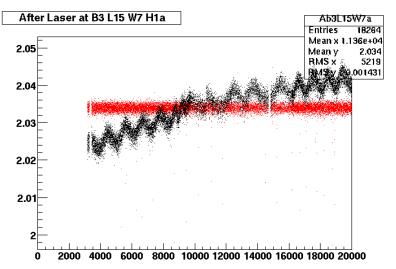




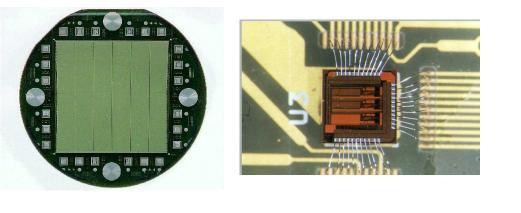
## Silicon Drift Tracker R&D Program, Rene Bellwied

UCLC proposal





 $8 \ \mu m$  in anode direction,  $13 \ \mu m$  in drift



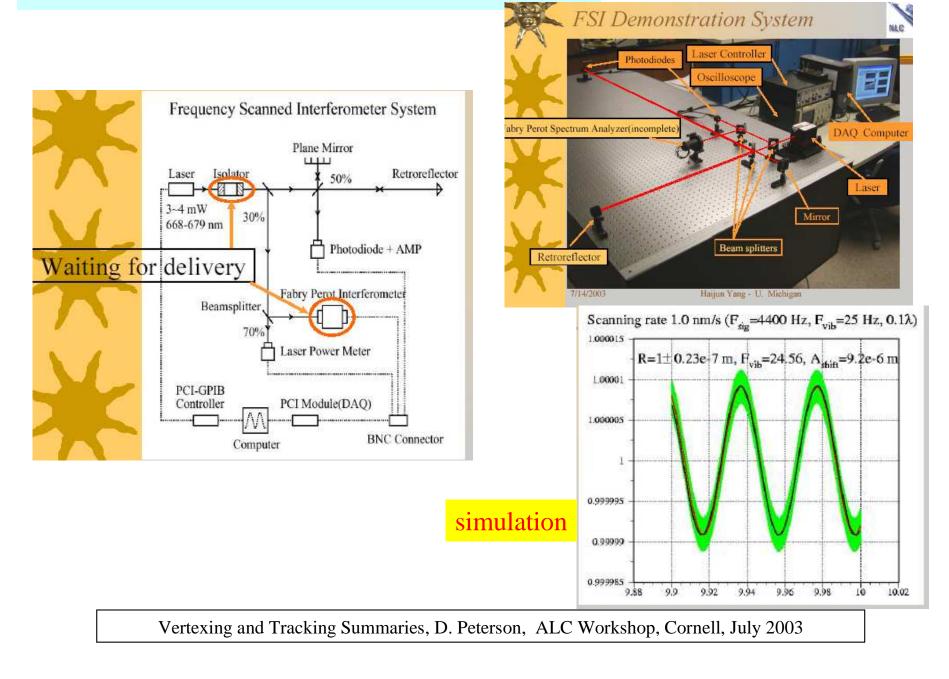


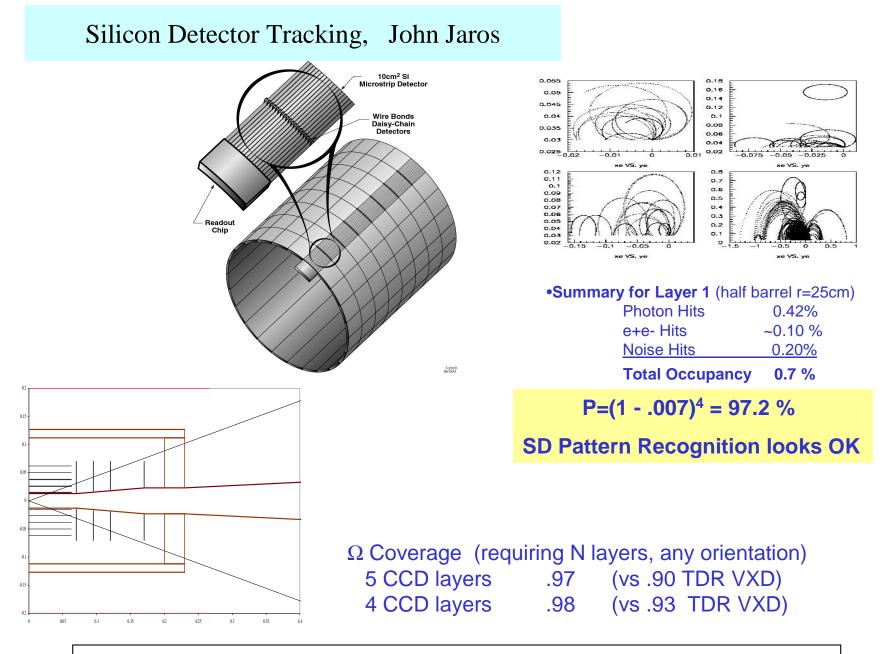
Proposed wafer R&D

Proposed front-end R&D

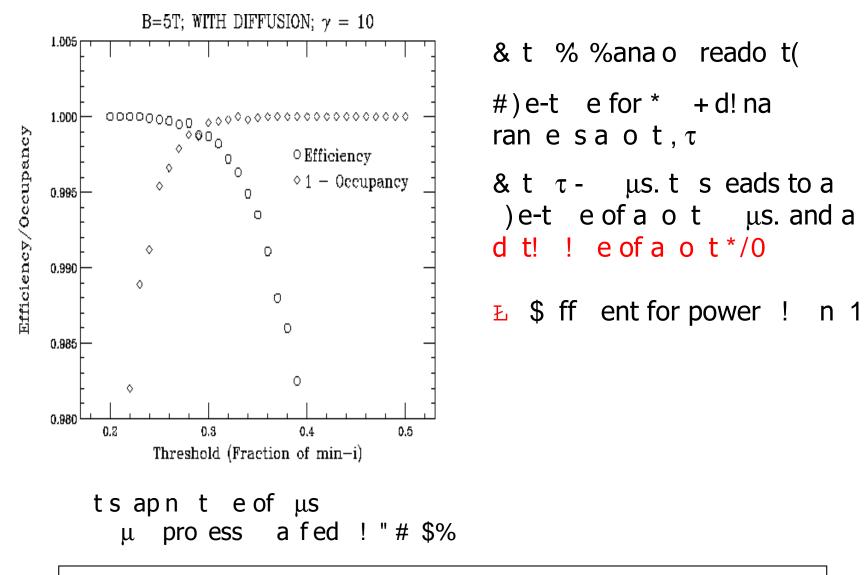
Proposed wafer R&D

# Frequency-Scanned Interferometry Haijun Yang





Long Shaping-Time Readout for Silicon Strips, Bruce Schumm



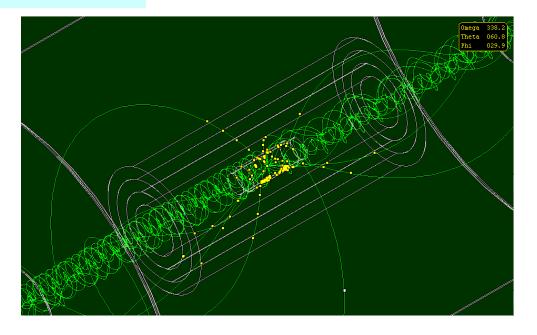
## Forward Tracking Simulation, Norman Graf

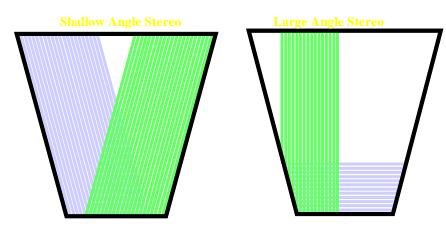
single crossing simulation (pairs only)

shown for vertex detector and Si tracker

will be applied to forward tracking

- Many open issues:
  - Tiling of disks with wafers:
    - Phi segmentation?
    - Radial segmentation?
  - Mix of Si pixel and μ-strip detectors?
  - If pixel, APD or CCD?
  - If μ-strip, double-sided or back-to-back?
  - Strip orientations within wedges.
    - Shallow- or large-angle stereo?





# South Carolina Tracking Plans, Achim W. Weidemann

#### LCRD proposal

# Planned Tracking Study

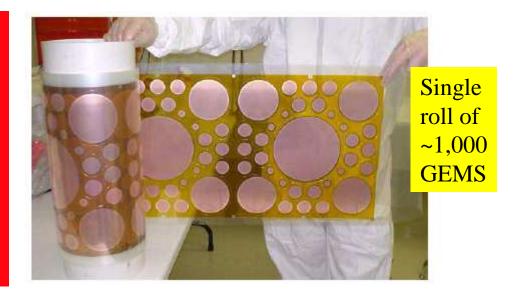
- Study existing tracking code
- Tracking efficiency, fake rates for existing trackers
- Compare different configurations
- Develop new tracker with Si strip planes
- Physics impact: Higgs, SUSY,... physics yields, resolutions

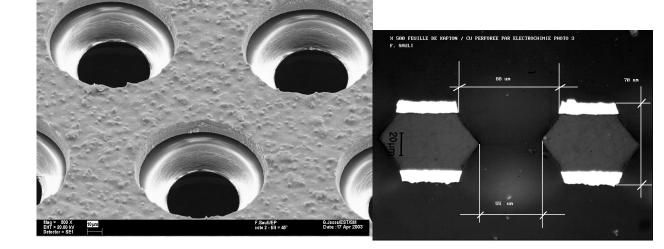
# Ian Shipsey

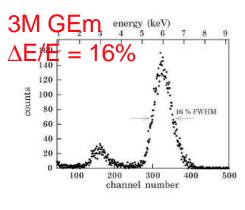
# 3M Microinterconnect Systems Division Reel-to-reel

process, rolls of 16<sup>2</sup> x16<sup>2</sup> templates of detachable GEMs in any pattern. Optional processes possible.

- First batch of 1,980 GEMs recently produced. Low cost per unit! (~2 USD/GEM not counting R&D)
- Two fabrication techniques (additive, substractive) tested.







Fe<sub>55</sub> spectrum